

ABSTRACT OF THE DISCLOSURE

In a semiconductor laser element having a plurality of semiconductor layers formed on a substrate, a groove-form concave portion is formed on the surface of the substrate opposite to the surface having the semiconductor layers. The concave portion is filled with metal having a higher heat conductivity higher than the substrate. The semiconductor laser element achieves improved heat dissipation characteristics and high reliability even under high-output operation.

RECORDED IN MICROGRAPHIC FORM BY OPTICAL MEANS  
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FOR THE USE OF THE APPLICANT  
IN THE PREPARATION OF A  
SEARCH CARD